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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Claims 1-16 (Canceled)

17. (Previously Presented) A method for manufacturing a semiconductor device comprising:

depositing a film over a substrate by repeatedly moving a first evaporation source and a second evaporation source in an X direction while moving the substrate in a Y direction at regular intervals,

wherein the first evaporation source and the second evaporation source are provided in a same chamber in which the film is deposited.

18. (Previously Presented) The method according to claim 17, wherein the semiconductor device is incorporated into an electronic apparatus selected from the group consisting of a video camera, a digital camera, a goggle display, a navigation system, an audio reproducing apparatus, a laptop computer, a game machine, a mobile computer, a cellular phone, a portable game machine, an electronic book, and an image reproducing apparatus.

19. (Previously Presented) A method for manufacturing a semiconductor device comprising:

depositing a film over a substrate by repeatedly moving the substrate in a Y direction at regular intervals while making a movement speed of a first evaporation source in an X direction and a movement speed of a second evaporation source in the X direction different,

wherein the first evaporation source and the second evaporation source are provided in a same chamber in which the film is deposited.

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20. (Previously Presented) The method according to claim 19, wherein the semiconductor device is incorporated into an electronic apparatus selected from the group consisting of a video camera, a digital camera, a goggle display, a navigation system, an audio reproducing apparatus, a laptop computer, a game machine, a mobile computer, a cellular phone, a portable game machine, an electronic book, and an image reproducing apparatus.

21. (Currently Amended) A method for manufacturing a semiconductor device comprising:

depositing a film over a substrate by moving reciprocating an evaporation source including first and second crucibles in the X direction while moving the substrate in the Y direction at a constant speed,

wherein each of the first and second crucibles includes a shutter.

22. (Previously Presented) The method according to claim 21, wherein the semiconductor device is incorporated into an electronic apparatus selected from the group consisting of a video camera, a digital camera, a goggle display, a navigation system, an audio reproducing apparatus, a laptop computer, a game machine, a mobile computer, a cellular phone, a portable game machine, an electronic book, and an image reproducing apparatus.

23. (Previously Presented) A method for manufacturing a semiconductor device comprising:

depositing an EL material over a substrate by repeatedly moving a first evaporation source and a second evaporation source in an X direction while moving the substrate in a Y direction at regular intervals,

wherein the first evaporation source and the second evaporation source are provided in a same chamber in which the EL material is deposited.

24. (Previously Presented) The method according to claim 23, wherein the semiconductor device is incorporated into an electronic apparatus selected from the group

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consisting of a video camera, a digital camera, a goggle display, a navigation system, an audio reproducing apparatus, a laptop computer, a game machine, a mobile computer, a cellular phone, a portable game machine, an electronic book, and an image reproducing apparatus.

25. (Previously Presented) A method for manufacturing a semiconductor device comprising:

depositing an EL material over a substrate by repeatedly moving the substrate in a Y direction at regular intervals while making a movement speed of a first evaporation source in an X direction and a movement speed of a second evaporation source in the X direction different,

wherein the first evaporation source and the second evaporation source are provided in a same chamber in which the EL material is deposited.

26. (Previously Presented) The method according to claim 25, wherein the semiconductor device is incorporated into an electronic apparatus selected from the group consisting of a video camera, a digital camera, a goggle display, a navigation system, an audio reproducing apparatus, a laptop computer, a game machine, a mobile computer, a cellular phone, a portable game machine, an electronic book, and an image reproducing apparatus.

27. (Currently Amended) A method for manufacturing a semiconductor device comprising:

depositing an EL material over a substrate by moving reciprocating an evaporation source including first and second crucibles in the X direction while moving the substrate in the Y direction at a constant speed,

wherein each of the first and second crucibles includes a shutter.

28. (Previously Presented) The method according to claim 27, wherein the semiconductor device is incorporated into an electronic apparatus selected from the group consisting of a video camera, a digital camera, a goggle display, a navigation system, an

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audio reproducing apparatus, a laptop computer, a game machine, a mobile computer, a cellular phone, a portable game machine, an electronic book, and an image reproducing apparatus.

29. (Previously Presented) The method according to claim 17, wherein at least one of the first evaporation source and the second evaporation source includes at least two crucibles arranged in the X direction.

30. (Previously Presented) The method according to claim 19, wherein at least one of the first evaporation source and the second evaporation source includes at least two crucibles arranged in the X direction.

31. (Currently Amended) The method according to claim 21, wherein the evaporation source includes at least two the first and second crucibles arranged in the X direction.

32. (Previously Presented) The method according to claim 23, wherein at least one of the first evaporation source and the second evaporation source includes at least two crucibles arranged in the X direction.

33. (Previously Presented) The method according to claim 25, wherein at least one of the first evaporation source and the second evaporation source includes at least two crucibles arranged in the X direction.

34. (Currently Amended) The method according to claim 27, wherein the evaporation source includes at least two the first and second crucibles arranged in the X direction.

35. (New) A method for manufacturing a semiconductor device comprising:
depositing a film over a substrate by moving a first evaporation source and a second evaporation source in the X direction while moving the substrate in the Y direction at a constant speed,
wherein at least one of the first evaporation source and the second evaporation source

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includes first and second crucibles, and
wherein each of the first and second crucibles includes a shutter.

36. (New) The method according to claim 35, wherein the semiconductor device is incorporated into an electronic apparatus selected from the group consisting of a video camera, a digital camera, a goggle display, a navigation system, an audio reproducing apparatus, a laptop computer, a game machine, a mobile computer, a cellular phone, a portable game machine, an electronic book, and an image reproducing apparatus.

37. (New) The method according to claim 35, wherein the first and second crucibles are arranged in the X direction.

38. (New) The method according to claim 35, wherein the first evaporation source and the second evaporation source are provided in a same chamber in which the film is deposited.

39. (New) A method for manufacturing a semiconductor device comprising:
depositing a film over a substrate by moving a first evaporation source and a second evaporation source in the X direction while moving the substrate in the Y direction at a constant speed,
wherein at least one of the first evaporation source and the second evaporation source includes first and second crucibles, and
wherein each of the first and second crucibles includes a shutter.

40. (New) The method according to claim 39, wherein the semiconductor device is incorporated into an electronic apparatus selected from the group consisting of a video camera, a digital camera, a goggle display, a navigation system, an audio reproducing apparatus, a laptop computer, a game machine, a mobile computer, a cellular phone, a portable game machine, an electronic book, and an image reproducing apparatus.

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41. (New) The method according to claim 39, wherein the first and second crucibles are arranged in the X direction.

42. (New) The method according to claim 39, wherein the first evaporation source and the second evaporation source are provided in a same chamber in which the EL material is deposited.